

SEMICONDUCTOR PACKAGE AND METHOD
FOR FABRICATING THE SAME

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5 Abstract of Disclosure

There is provided a semiconductor package and method for fabricating the same. An embodiment of the semiconductor package includes: a semiconductor chip having a first face and a second face, the first face having a plurality of input/output pads formed thereon; a circuit board composed of a resin film having a first face and a second face, a circuit pattern layer including a plurality of bond fingers and ball lands, and a cover coat covering the circuit pattern layer and selectively exposing the plurality of bond fingers and ball lands, the circuit pattern layer being formed on the first face of the resin film, the circuit board having a through hole at the center thereof, the semiconductor chip being placed in the through hole; electrical connection means for electrically connecting the input/output pads of the semiconductor chip to the bond fingers of the circuit board; an encapsulant for encapsulating the semiconductor chip, connection means and a part of the circuit board; and a plurality of conductive balls fused to the circuit board. Accordingly, the semiconductor package becomes very thin and its heat spreading performance is improved.